

C.F.R. §§ 1.16 to 1.21 be required for any reason, the Assistant Commissioner is authorized to deduct said fees from Deposit Account No. 50-0786/2000.075200/DCD. If any other such fees are due, other than the issue fee, the Assistant Commissioner is authorized to deduct such fees required under 37 C.F.R. §§ 1.16 to 1.21 from Deposit Account No. 50-0786/2000.075200/DCD.

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.

### AMENDMENT

Please make the following amendments:

#### IN THE SPECIFICATION:

Enclosed are substitute specification pages that correct certain informalities in the original typescript. A marked-up version of the pages is also provided indicating the amendments made. The paragraphs on pages 8 and 9 attached hereto should replace the corresponding paragraphs on pages 8 and 9 of the original specification. Applicants certify no new matter is introduced by the entry of this amendment.

#### IN THE CLAIMS:

Please cancel claims 3 and 14.

Please replace the previous version of claims 1 and 6 with the following clean version:

1. (Once Amended) A method of controlling a conductive layer deposition process, comprising:  
 depositing a conductive layer above a first semiconductor wafer based upon a deposition recipe;

measuring a thickness of the conductive layer deposited on the semiconductor wafer;

R<sup>1</sup> determining whether the measured thickness of the conductive layer is within a predetermined tolerance; and

revising at least one parameter selected from the group consisting of a chemical concentration of an electroplating bath and an anode-cathode spacing of the deposition recipe if the measured thickness of the conductive layer is not within the predetermined tolerance.

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6. (Once Amended) A method of controlling a conductive layer deposition process, comprising:

depositing a conductive layer above a first semiconductor wafer based upon a deposition recipe;

measuring a thickness of the conductive layer at a plurality of locations;

R<sup>2</sup> calculating a value representing the measured thickness measured at the plurality of locations;

determining whether the calculated value is within a predetermined tolerance; and

revising at least one parameter selected from the group consisting of a chemical concentration of an electroplating bath and an anode-cathode spacing of the deposition recipe based upon at least the calculated value if the calculated value is not within the predetermined tolerance.

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